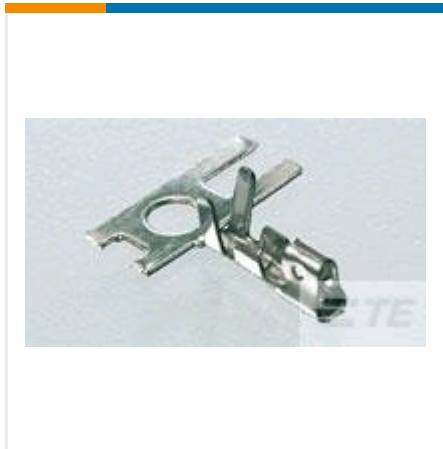




CONNECTORS

WIRE-TO-BOARD CONNECTOR CONTACTS



✓ Active

TE CONNECTIVITY (TE)

2.0mm,Crimp,Contact

HPI | HDR

1735801-1

TE Internal Number: 1735801-1

EU RoHS Compliant

EU ELV Compliant

Contact Type Socket

Connector System Wire-to-Board

Centerline (Pitch) 2 mm [.079 in]

Wire/Cable Size (AWG) 30 – 24

Wire/Cable Size (mm²) .05 – .02

[↓ PRODUCT DRAWING](#)
English

[↓ 3D PDF](#)

DOCUMENTATION

Product Drawings

2.0MM PITCH HPI CRIMP CONTACT

PDF

English

CAD Files

3D PDF

PDF

3D

Customer View Model

2D_DXF.ZIP

English

Customer View Model

3D_IGS.ZIP

English

Customer View Model

3D_STP.ZIP

English

Product Specifications

Application Specification

AMP 2.0mm Pitch HPI Wire To Board System.

PDF

English

Product Specification

HPI CONNECTOR, 2.0MM PITCH, LOCKING TYPE

PDF

English

Product Environmental Compliance

TE Material Declaration

MD_1735801-1_03082017529_dmtec

PDF

English

FEATURES



Please review product documents or [contact us](#) for the latest agency approval information.

Please Note: Use the Product Drawing for all design activity.

Product Type Features

Connector System Wire-to-Board

Connector & Contact Terminates To Wire & Cable

Wire/Cable Type Discrete Wire

Product Type Contact

Electrical Characteristics

Operating Voltage (VDC) 250

Operating Voltage (VAC) 250

Contact Features

Crimp Area Plating Thickness (µin) 80

Contact Type Socket

Contact Mating Area Plating Material Tin

Contact Current Rating (Max) (A) 3

Crimp Area Plating Material Pre-Tin

Contact Base Material Phosphor Bronze

Contact Plating Material Tin

Housing Features

Centerline (Pitch) 2 mm [.079 in]

Dimensions

Wire/Cable Size (AWG) 30 – 24

Wire/Cable Size (mm²) .05 – .02

Usage Conditions

Operating Temperature Range -25 – 105 °C [-13 – 221 °F]

Operation/Application

For Use With 1735447-x- 2041423-x

Packaging Features

Packaging Method Reel

Packaging Quantity 10000

PRODUCT COMPLIANCE



Statement of Compliance

Statement of Compliance

PDF
